

VOLTAGE RANGE: 50 - 800V

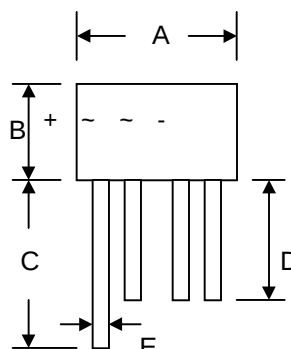
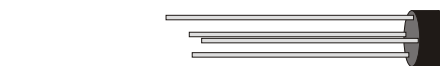
CURRENT: 1.5 A

Features

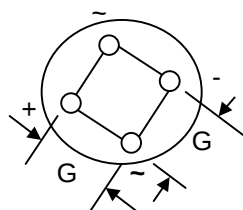
- Diffused Junction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards

Mechanical Data

- Case: WOB, Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 1.1 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



WOB		
Dim	Min	Max
A	8.60	9.10
B	5.0	5.50
C	27.9	—
D	25.4	—
E	0.71	0.81
G	4.60	5.60
All Dimensions in mm		



Maximum Ratings and Electrical Characteristics T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

RATING	SYMBOL	RB150	RB151	RB152	RB154	RB156	RB158	UNIT
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	Volts
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	Volts
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	Volts
Maximum Average Forward Current T _c =50°C	I _{F(AV)}	1.5						Amps.
Peak Forward Surge Current, Single half sine wave Superimposed on rated load (JEDEC Method)	I _{FSM}	40						Amps.
Maximum Forward Voltage per Diode at I _F = 1 Amp.	V _F	0.95						Volt
Maximum DC Reverse Current at Rated DC Blocking Voltage	I _R	10						μA
		100						μA
Typical Thermal Resistance (Note 1)	R _{θJL}	15						°C/W
Operating Junction Temperature Range	T _J	- 40 to + 140						°C
Storage Temperature Range	T _{STG}	- 40 to + 140						°C

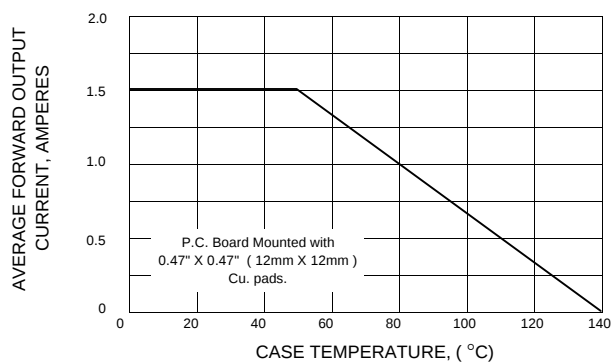
Notes :

- 1) Thermal resistance from Junction to lead mounted on P.C. Board with 0.47" X 0.47" (12mm X 12mm) Cu pads.

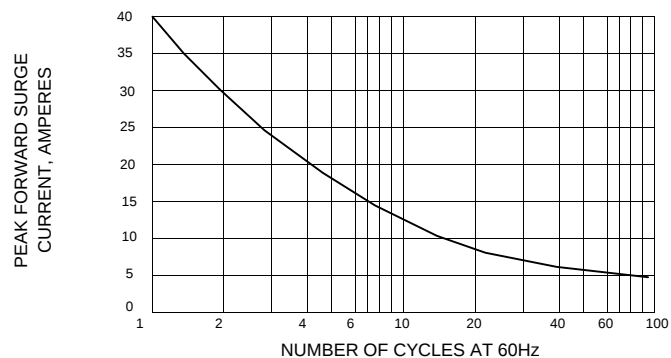


RATING AND CHARACTERISTIC CURVES (RB150 - RB158)

**FIG.1 - DERATING CURVE FOR OUTPUT
RECTIFIED CURRENT**



**FIG.2 - MAXIMUM NON-REPETITIVE PEAK
FORWARD SURGE CURRENT**



**FIG.3 - TYPICAL FORWARD CHARACTERISTICS
PER DIODE**

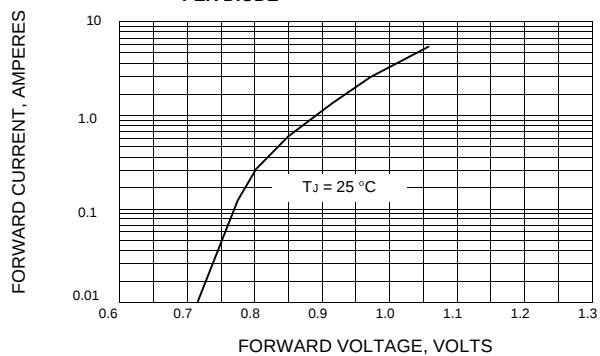


FIG.4 - TYPICAL REVERSE CHARACTERISTICS

